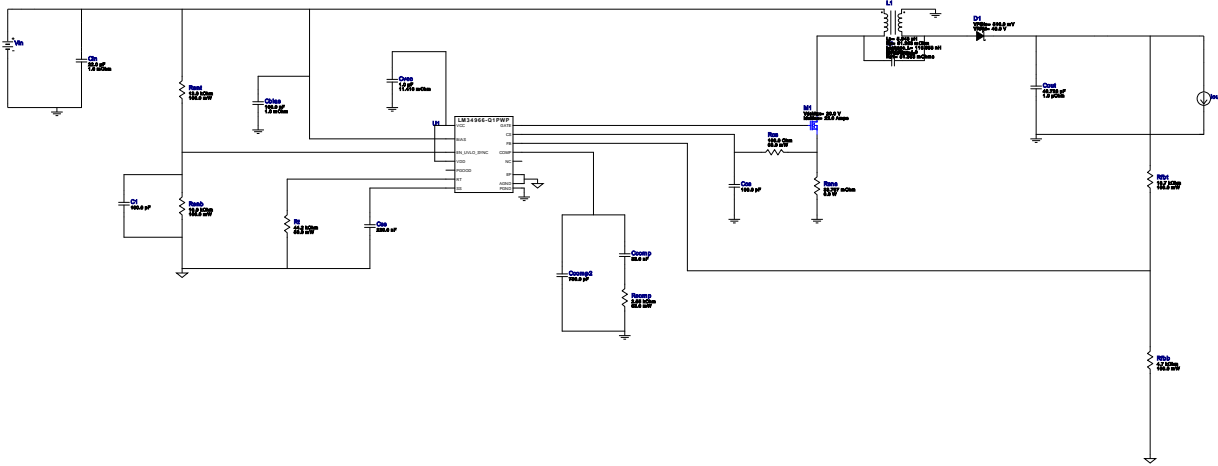


VinMin = 3.7V
VinMax = 4.2V
Vout = 5.0V
Iout = 0.8A

Device = LM34966QPWPRQ1
Topology = SEPIC
Created = 2023-03-09 10:53:28.034
BOM Cost = NA
BOM Count = 22
Total Pd = 0.42W

WEBENCH® Design Report

Design : 1 LM34966QPWPRQ1
LM34966QPWPRQ1 3.7V-4.2V to 5.00V @ 0.8A









Design Alerts

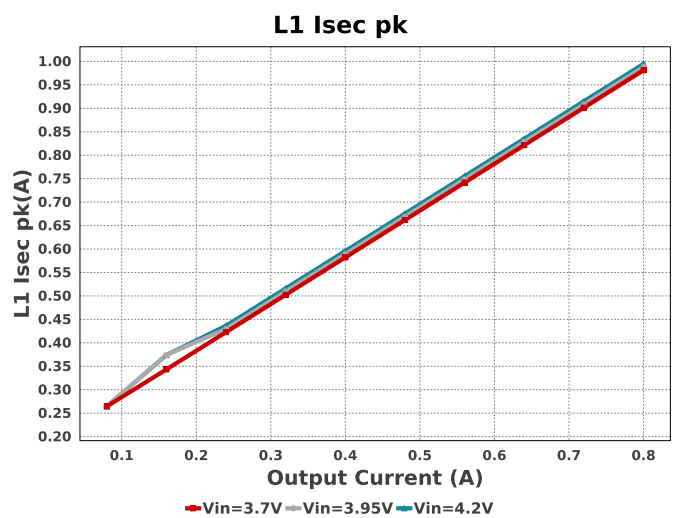
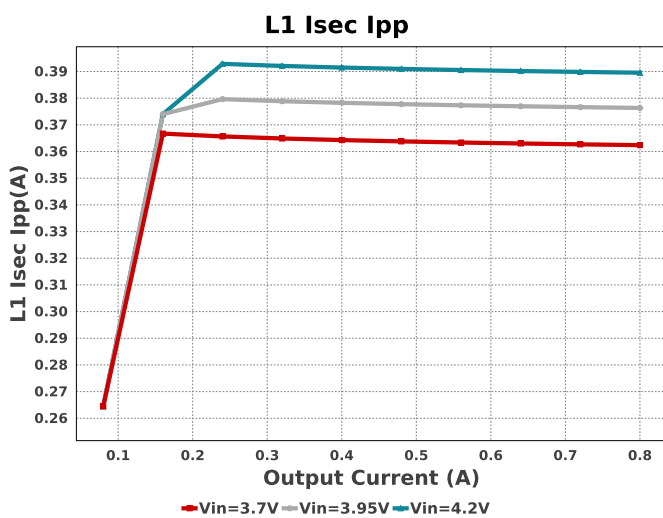
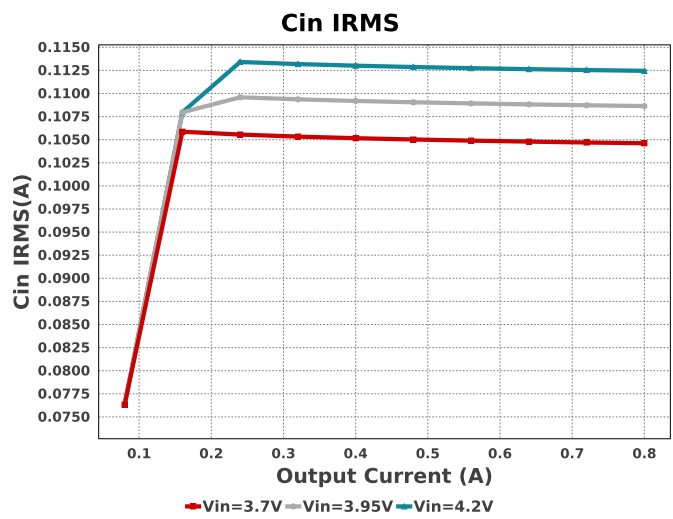
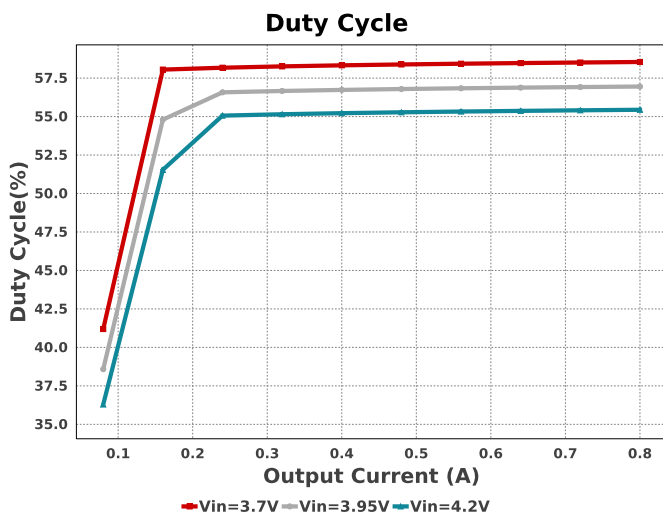
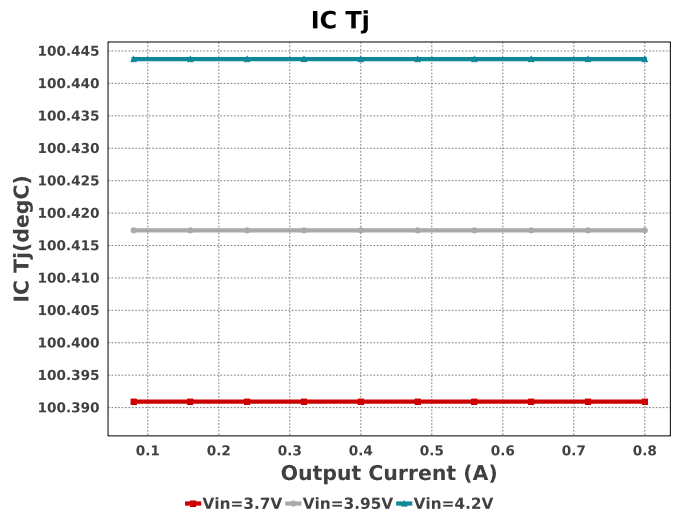
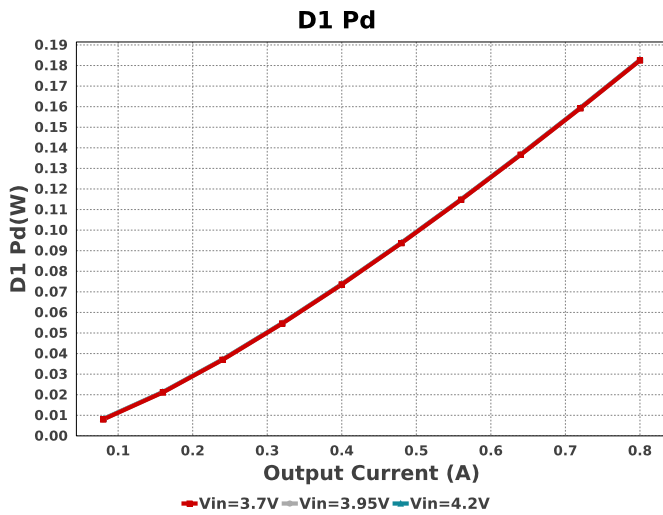
Component Selection Information

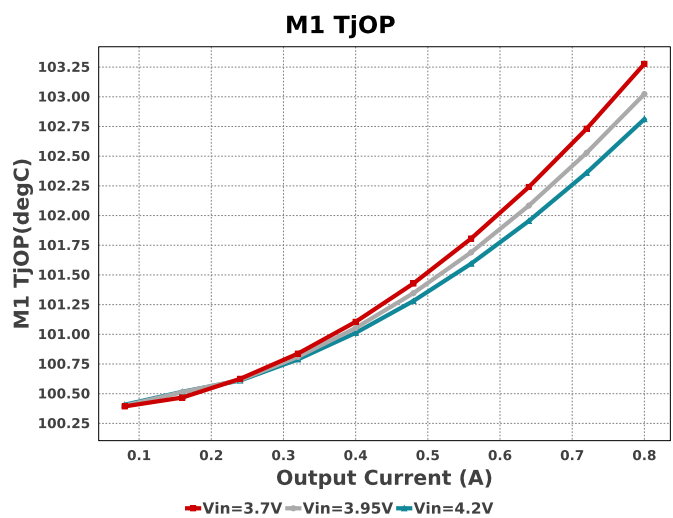
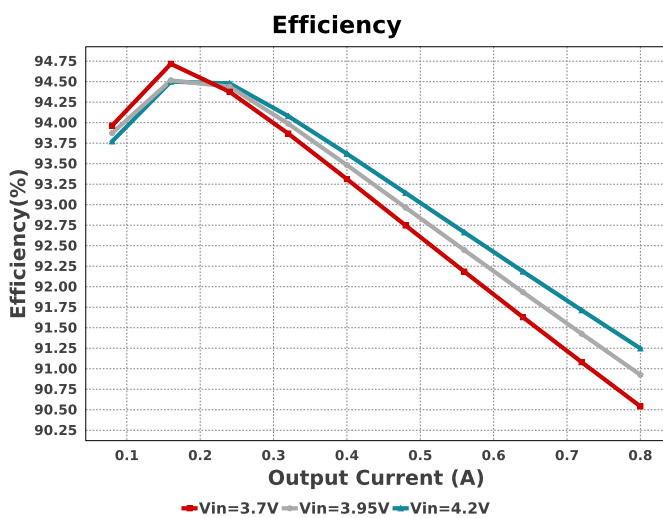
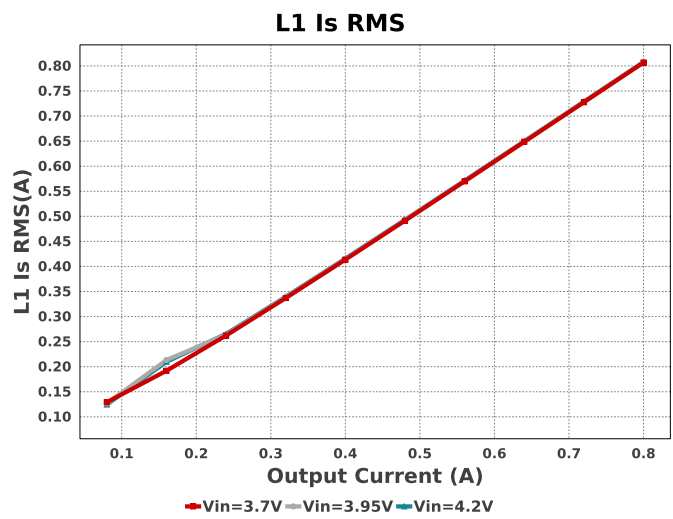
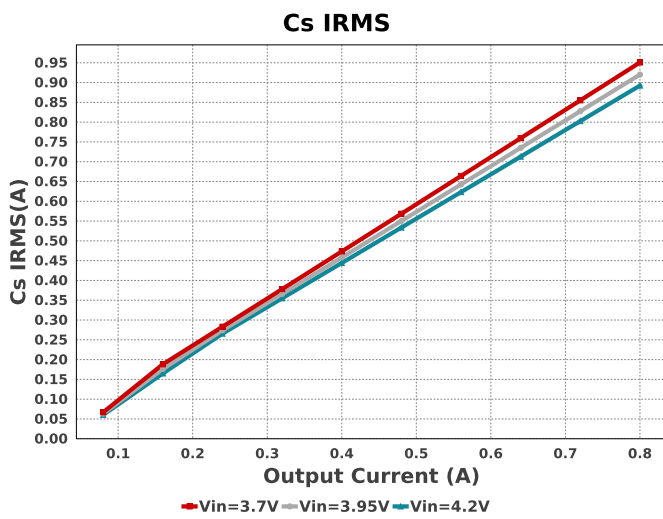
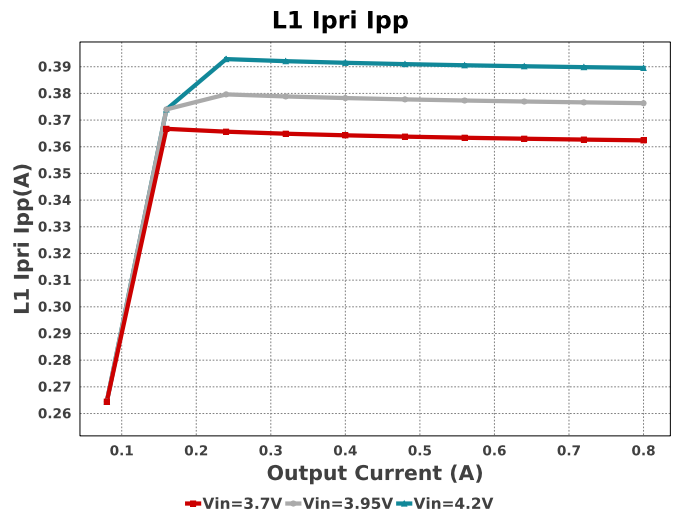
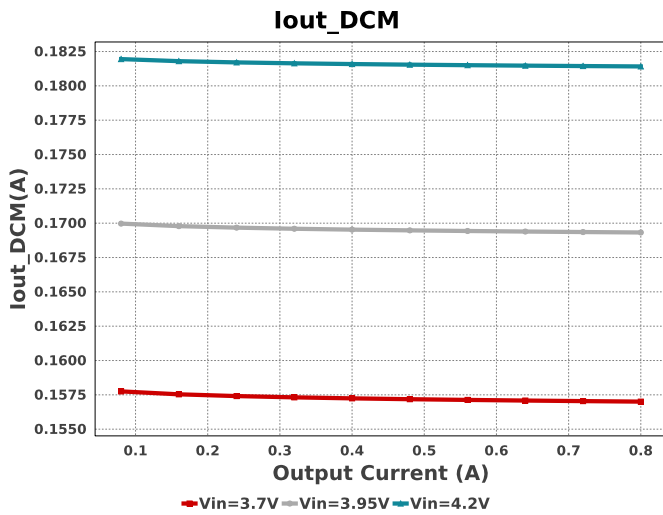
The LM34966-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application. View WEBENCH(R) Disclaimer

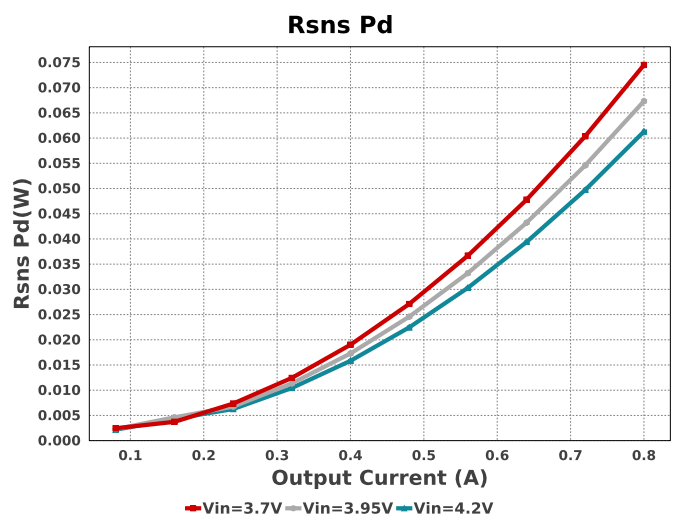
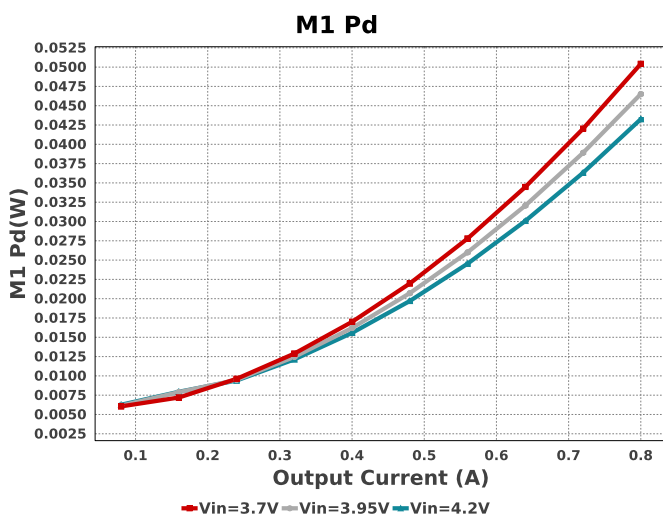
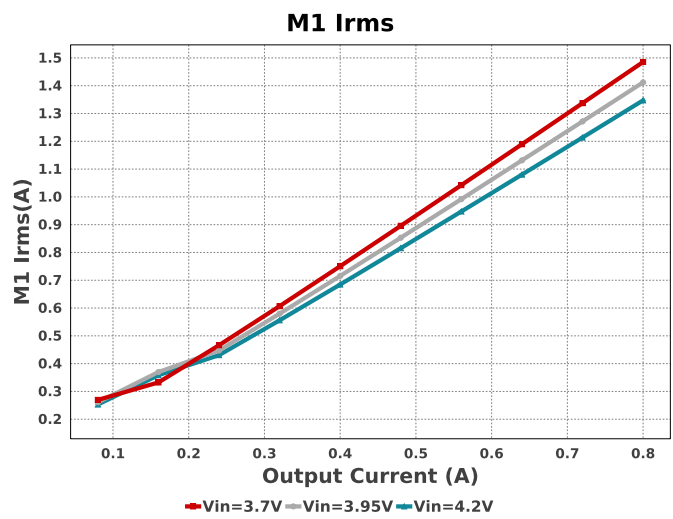
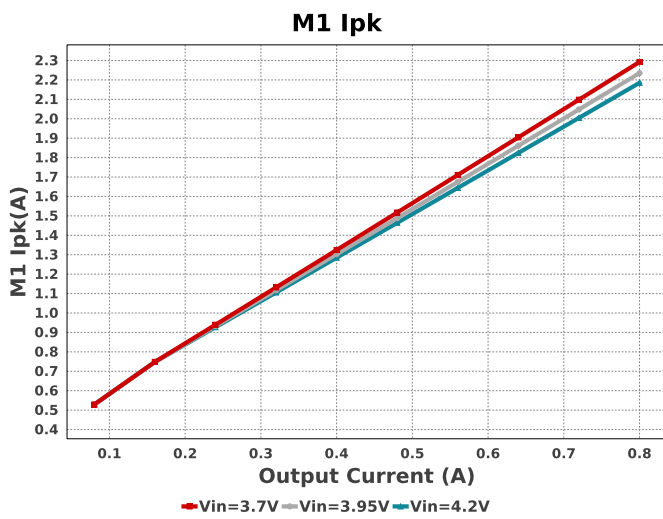
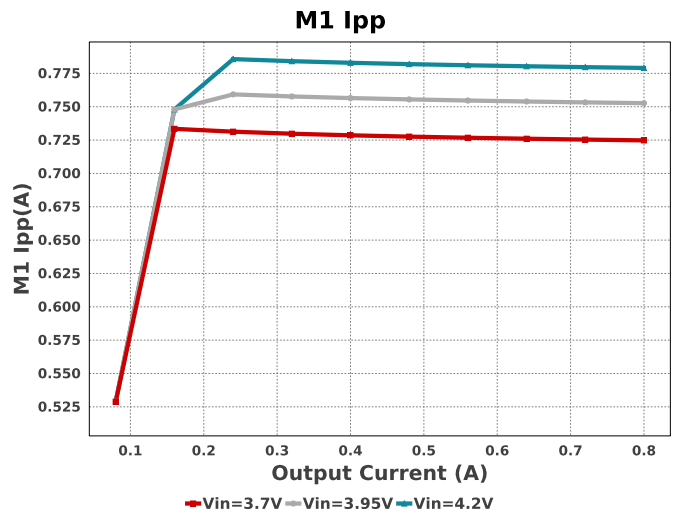
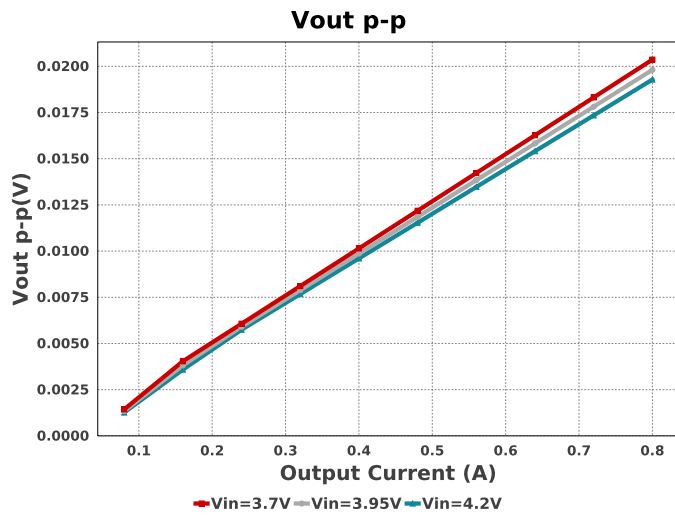
Electrical BOM

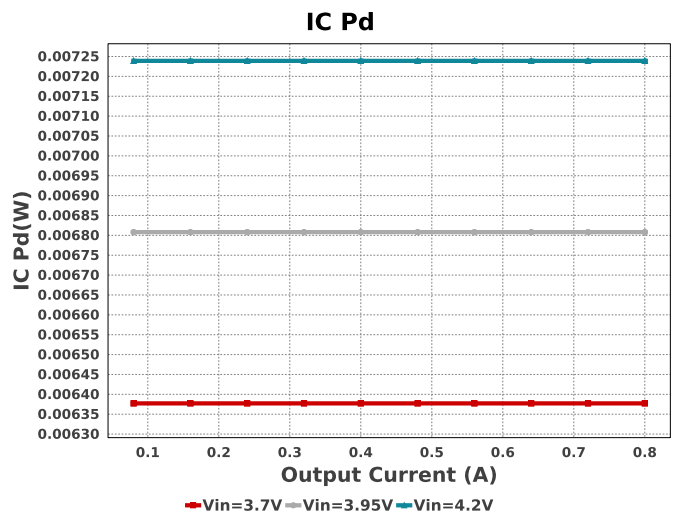
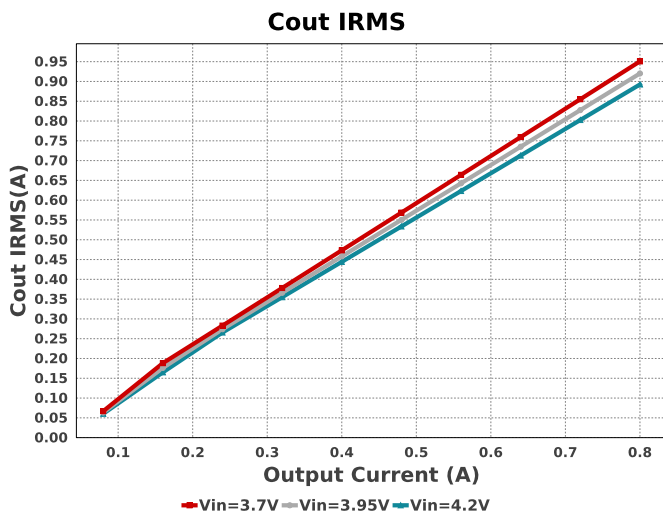
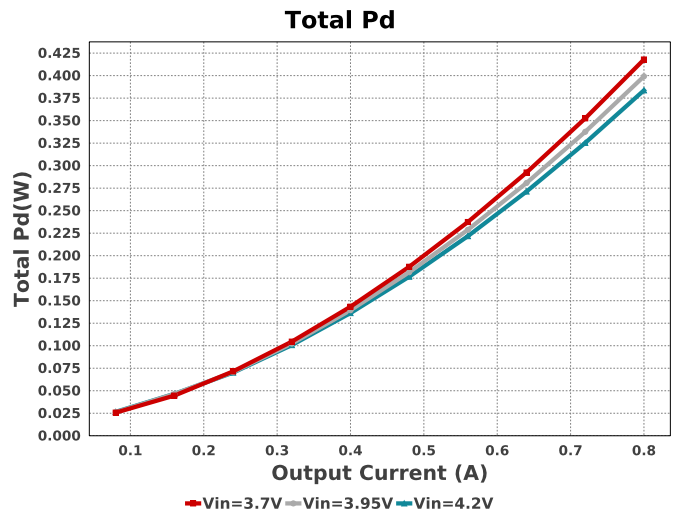
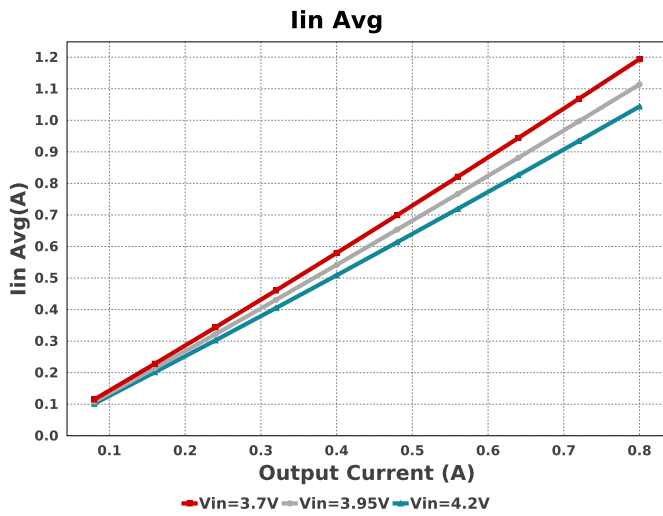
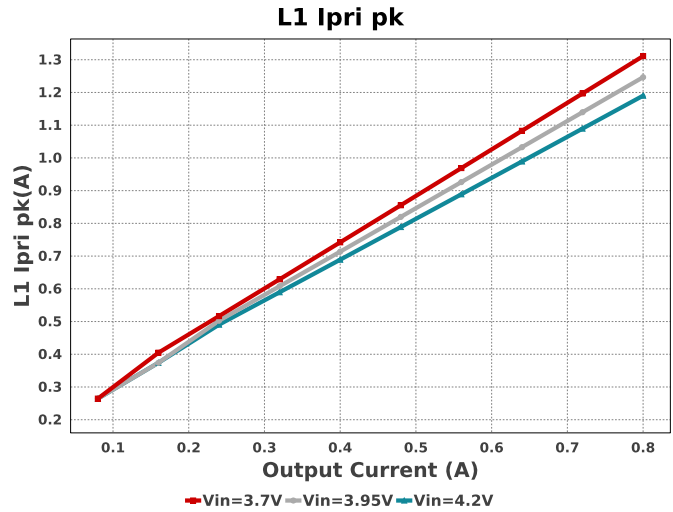
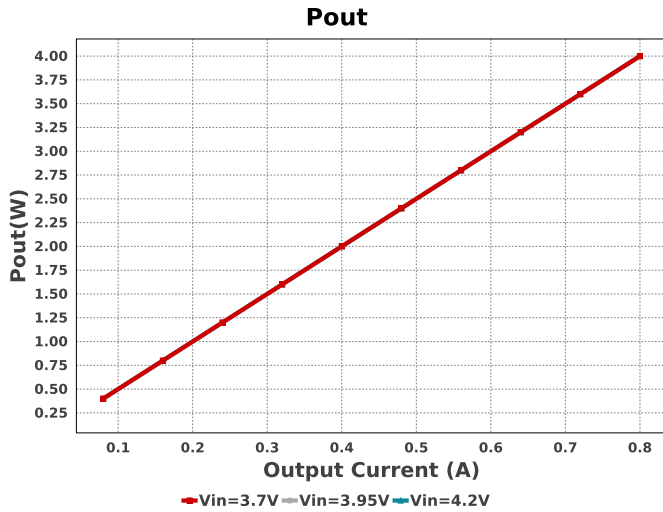
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
C1	TDK	C0402C0G1C101J020BC Series= C0G/NP0	Cap= 100.0 pF VDC= 16.0 V IRMS= 0.0 A	1	\$0.03	01005 2 mm ²
Cbias	MuRata	GRM155R70J104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 6.3 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
Ccomp	TDK	CGA4J2C0G1H333J125AA Series= C0G/NP0	Cap= 33.0 nF VDC= 50.0 V IRMS= 0.0 A	1	\$0.08	0805 7 mm ²
Ccomp2	MuRata	GRM1555C1H751GA01D Series= C0G/NP0	Cap= 750.0 pF VDC= 50.0 V IRMS= 0.0 A	1	\$0.04	0402 3 mm ²
Ccs	TDK	C0402C0G1C101J020BC Series= C0G/NP0	Cap= 100.0 pF VDC= 16.0 V IRMS= 0.0 A	1	\$0.03	01005 2 mm ²
Cin	TDK	C2012X7S1A226M125AC Series= X7S	Cap= 22.0 uF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.26	0805 7 mm ²
Cout	CUSTOM	CUSTOM Series= ?	Cap= 46.733 uF ESR= 1.0 uOhm VDC= 10.0 V IRMS= 1.1651 A	1	NA	CUSTOM 0 mm ²
Cs	TDK	C2012X6S1C685K125AC Series= X6S	Cap= 6.8 uF ESR= 3.795 mOhm VDC= 16.0 V IRMS= 3.3493 A	1	\$0.11	0805 7 mm ²

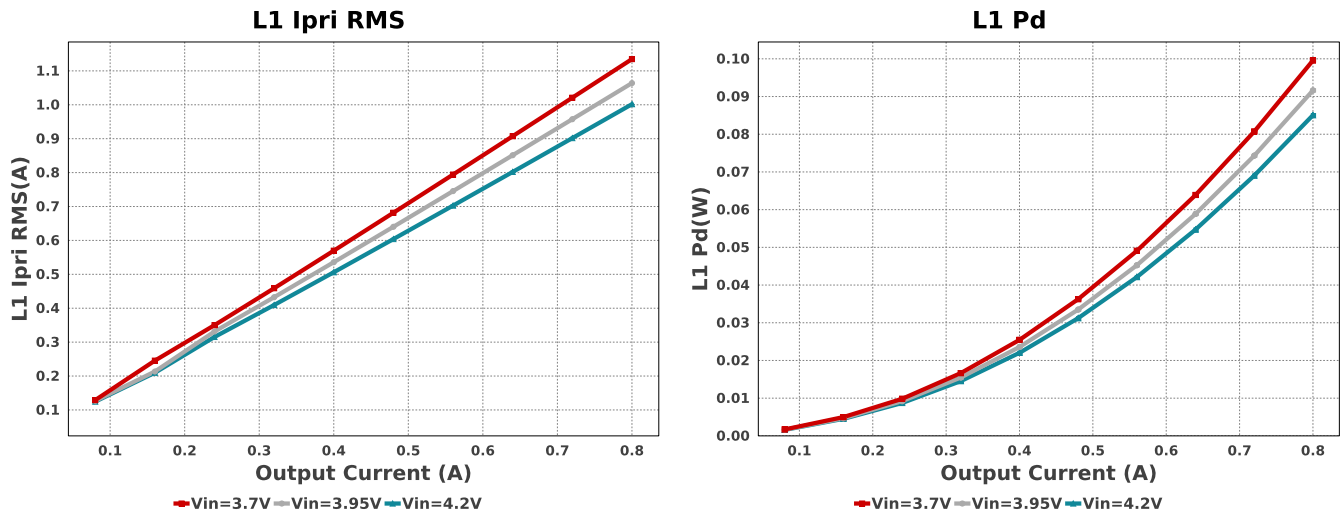
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Css	Kemet	C1210C224J3GACTU Series= C0G/NP0	Cap= 220.0 nF VDC= 5.0 V IRMS= 0.0 A	1	\$1.63	 1210 15 mm ²
Cvcc	TDK	C1005X6S1C105K050BC Series= X6S	Cap= 1.0 uF ESR= 11.416 mOhm VDC= 16.0 V IRMS= 1.483 A	1	\$0.02	 0402 3 mm ²
D1	Vishay-Semiconductor	50WQ04FNPBF	VF@Io= 510.0 mV VRRM= 40.0 V	1	\$0.40	 DPAK 102 mm ²
L1	CUSTOM	CUSTOM	Lp= 5.843 uH Rp= 51.363 mOhm Leakage_L= 116.858 nH Ns1toNp= 1.0 Rs1= 51.363 mOhms	1	NA	CUSTOM 0 mm ²
M1	Texas Instruments	CSD15571Q2	VdsMax= 20.0 V IdsMax= 22.0 Amps	1	\$0.10	 DQK0006C 9 mm ²
Rcomp	Vishay-Dale	CRCW04022K55FKED Series= CRCW..e3	Res= 2.55 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Rcs	Vishay-Dale	CRCW0402100RFKED Series= CRCW..e3	Res= 100.0 Ohm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Renb	Susumu Co Ltd	RG1608P-103-B-T5 Series= RG1608	Res= 10.0 kOhm Power= 100.0 mW Tolerance= 0.1%	1	\$0.04	 0603 5 mm ²
Rent	Yageo	RT0603BRD0713KL Series= ?	Res= 13.0 kOhm Power= 100.0 mW Tolerance= 0.1%	1	\$0.04	 0603 5 mm ²
Rfbb	Susumu Co Ltd	RG1608P-472-B-T5 Series= RG1608	Res= 4.7 kOhm Power= 100.0 mW Tolerance= 0.1%	1	\$0.04	 0603 5 mm ²
Rfbt	Susumu Co Ltd	RG1608P-1872-B-T5 Series= RG1608	Res= 18.7 kOhm Power= 100.0 mW Tolerance= 0.1%	1	\$0.06	 0603 5 mm ²
Rsns	CUSTOM	CUSTOM Series= ?	Res= 33.767 mOhm Power= 0.0 W Tolerance= 0.0%	1	NA	CUSTOM 0 mm ²
Rt	Vishay-Dale	CRCW020144K2FNED Series= ?	Res= 44.2 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	 0201 2 mm ²
U1	Texas Instruments	LM34966QPWPRQ1	Switcher	1	\$0.83	 PWP0014H 59 mm ²











Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	104.614 mA	Capacitor	Input capacitor RMS ripple current
2.	Cout IRMS	950.749 mA	Capacitor	Output capacitor RMS ripple current
3.	Cs IRMS	950.749 mA	Capacitor	Coupling capacitor RMS ripple current
4.	M1 Ipk	2.292 A	Current	M1 peak current.
5.	D1 Pd	182.5 mW	Diode	Output Diode Power Dissipation
6.	IC Pd	6.377 mW	IC	IC power dissipation
7.	IC Tj	100.391 degC	IC	IC junction temperature
8.	ICThetaJA	61.3 degC/W	IC	IC junction-to-ambient thermal resistance
9.	Iin Avg	1.194 A	IC	Average input current
10.	M1 Irms	1.485 A	Mosfet	M1 MOSFET Irms
11.	M1 Pd	50.42 mW	Mosfet	M1 MOSFET total power dissipation
12.	M1 TJOP	103.277 degC	Mosfet	M1 MOSFET junction temperature
13.	D1 Pd	182.5 mW	Power	Output Diode Power Dissipation
14.	IC Pd	6.377 mW	Power	IC power dissipation
15.	L1 Pd	99.57 mW	Power	Power Dissipation in the Inductor
16.	M1 Pd	50.42 mW	Power	M1 MOSFET total power dissipation
17.	Rsns Pd	74.497 mW	Power	Current Limit Sense Resistor Power Dissipation
18.	Total Pd	417.88 mW	Power	Total Power Dissipation
19.	Rsns Pd	74.497 mW	Resistor	Current Limit Sense Resistor Power Dissipation
20.	BOM Count	22	System	Total Design BOM count
Information				
21.	Duty Cycle	58.547 %	System	Duty cycle
Information				
22.	Efficiency	90.541 %	System	Steady state efficiency
Information				
23.	FootPrint	374.0 mm ²	System	Total Foot Print Area of BOM components
Information				
24.	Frequency	489.425 kHz	System	Switching frequency
Information				
25.	Iout	800.0 mA	System	Iout operating point
Information				
26.	Iout_DCM	157.006 mA	System	Approximate Current below which DCM mode of operation will begin
Information				
27.	M1 Ipp	724.786 mA	System	M1 ripple pk-pk.
Information				
28.	Mode	CCM	System	Conduction Mode
Information				
29.	Pout	4.0 W	System	Total output power
Information				
30.	Total BOM	NA	System	Total BOM Cost
Information				
31.	Vin	3.7 V	System	Vin operating point
Information				
32.	Vout	5.0 V	System	Operational Output Voltage
Information				
33.	Vout Actual	4.979 V	System	Vout Actual calculated based on selected voltage divider resistors
Information				
34.	Vout Tolerance	961.269 m%	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
Information				
35.	Vout p-p	20.362 mV	System	Peak-to-peak output ripple voltage
Information				
36.	L1 Ipri Ipp	362.393 mA	Transformer	L1 primary side ripple pk-pk.

#	Name	Value	Category	Description
37.	L1 Ipri RMS	1.135 A	Transformer	L1 primary rms current.
38.	L1 Ipri pk	1.311 A	Transformer	L1 primary pk current.
39.	L1 Is RMS	806.811 mA	Transformer	L1 secondary rms current
40.	L1 Isec lpp	362.393 mA	Transformer	L1 secondary side ripple pk-pk.
41.	L1 Isec pk	981.196 mA	Transformer	Peak current in L1 secondary
42.	L1 Pd	99.57 mW	Transformer	Power Dissipation in the Inductor

Design Inputs

Name	Value	Description
Iout	800.0 m	Maximum Output Current
VinMax	4.2	Maximum input voltage
VinMin	3.7	Minimum input voltage
Vout	5.0	Output Voltage
base_pn	LM34966-Q1	Base Product Number
source	DC	Input Source Type
Ta	100.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of $L1$ before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

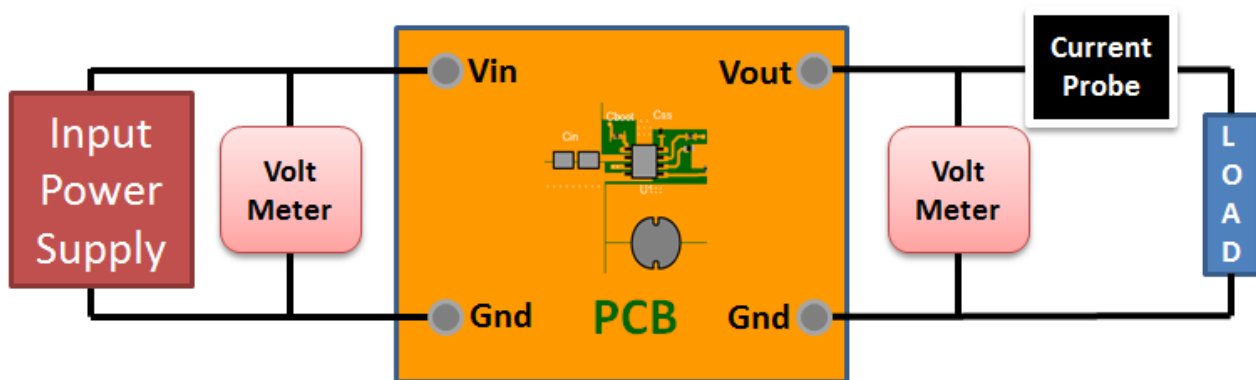
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 3.7V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. The LM34966-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application
2. Master key : 8203A6C6CAD8EBA8BF27793E47B632A6[v1]
3. **LM34966-Q1** Product Folder : <http://www.ti.com/product/LM34966%2DQ1> : contains the data sheet and other resources.

Important Notice and Disclaimer

TI provides technical and reliability data (including datasheets), design resources (including reference designs), application or other design advice, web tools, safety information, and other resources AS IS and with all faults, and disclaims all warranties. These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

Providing these resources does not expand or otherwise alter TI's applicable Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with TI products.